

COOLPad® CP1015FG

Interface pads



Description

COOLPad® is a line of high performance thermal interface pads, developed to address the industry's growing requirements for easy application, low levels of thermal resistance and high conformability, even at the most challenging and uneven surfaces. COOLPad® is specially suitable for applications with low clamping forces between the heat generating component and the heat dissipation surface.



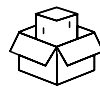
Features

- Low Thermal Resistance
- High Conformability
- Electrically Insulating
- RoHS, REACH and compliant"



Applications

- Electronic components like LEDs, CPUs, MOS
- Mobiles, Laptops, Tablets
- Electrical Vehicle Batteries
- Power devices and modules"



Delivery Format

- Sheets of 200x400m
- Die-cut parts"



Typical Properties

Properties	Standard	Unit	CP1015FG
Color	-	-	Grey
Carrier Type	-	-	Silicon
Carrier Reinforcement			Yes (Fiber Glass)
Thickness	ASTM D374	mm (inch)	0,25-5,0 (0,010-0,20)
Density	ASTM D792	g/cm ³	2,30
Thermal Conductivity	ASTM D5470	W/m.k	1,00
Volume Resistance	ASTM D257	ohms.cm	3.1*10 ¹¹
Thermal Resistance (50psi)	ASTM D5470	°C-in ² / W	0,51
Hardness	Shore C	-	30,00
Thermal Resistance	ASTM D5470	°C	-60 to 200
Dielectric Strength	ASTM D149	kV/mm	> 4,0
Shelf Life	-	-	5 years